

Enplas Simulation Technology

We are striving for further advancement in product engineering & design with the means of 3-dimensional CAD simulation capabilities for solutions in connections technology.

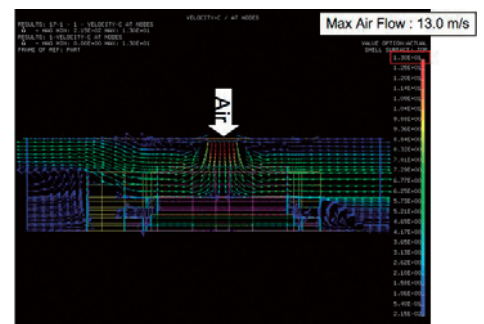
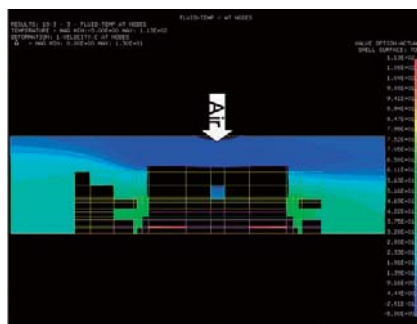
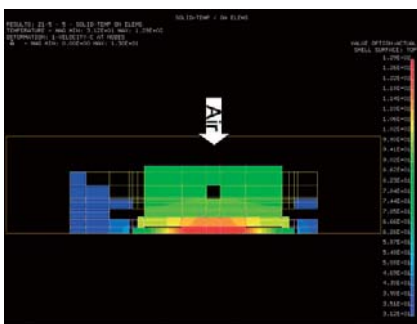
- New B/I and Test socket engineering and design process for high reliability and quality products.
- Socket designs for new devices to operate at increasing power, speed, life performance and controlled temperature level in B/I & T.
- Fine pitch products in small space with capability to handle power and solutions for low thermal resistance and cooling interface.
- Excellent design tools for high-end products in shorter development time to market.- Economical socket design solutions in HVM.

Thermal Simulation

Analyze thermal dissipation properties of Heat Sink materials by simulation to optimize Heat Sink Design and socket air convection flow in Burn-in.

熱解析

パッケージの発熱に対し、ヒートシンクによる放熱性を検証することにより、材質、形状を最適化します。

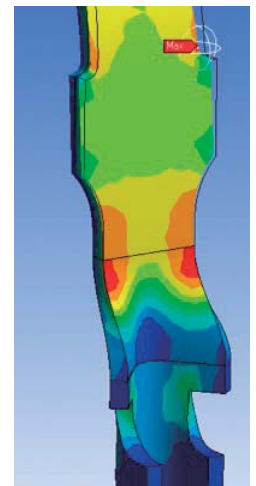
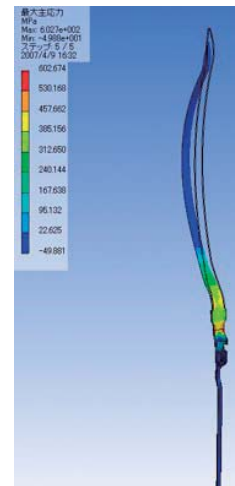
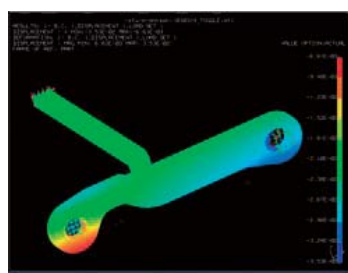
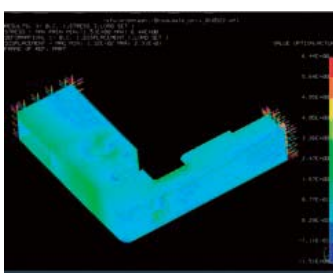
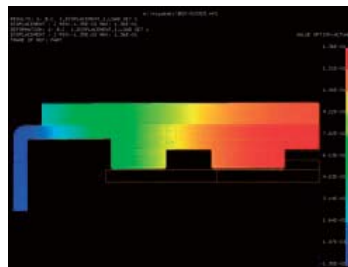
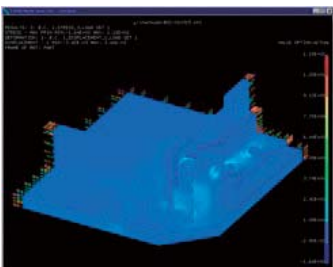


Stress & Deflection Simulation

Analyze stress and deflection points of each component in socket designs.

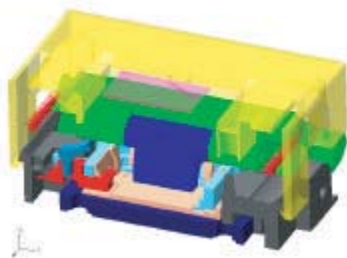
強度解析

成型部品、コンタクトピンの強度解析を行い ICソケットの設計に反映させます。



3D Dynamic Solid Simulation

Analyze Burn-In Socket actuation in complex structural designs. Simulation process increases efficiency in development time, resulting in high quality Burn-In Sockets.



3D動作検証

ICソケット完成品を立体透視化し、機構の動作検証を行います。

Electrical Performance Contact Simulation

Contact Pin structural and design analysis for high frequency electrical applications.

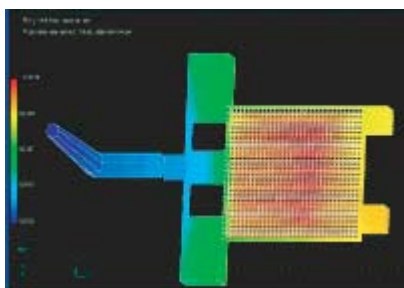
電気的性能確認

IC高周波帯域におけるコンタクトピンの対応状況を解析します。



Plastic Injection Mold Flow Simulation

Analyze plastic material flow in mold cavities and fill-up time, weld, gate and core positions designed for efficiency in plastic injection mold tooling.



流動解析

金型成型による樹脂部品の流動解析を行います。

Tolerance Simulation

Analyze matching condition in IC packages, mechanisms, and other components with statistical techniques such as Monte Carlo

公差解析

パッケージとICソケットの適合性を確認できます。

